

L Number	Hits	Search Text	DB	Time stamp
1	1	"10/028289"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:17
2	33519	passivation near6 (film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:03
3	10	(passivation near6 (film or layer)) near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:21
4	250	(passivation near6 (film or layer)) near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:21
5	148	((passivation near6 (film or layer)) near6 seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:30
6	26	349\$.ccls. and (((passivation near6 (film or layer)) near6 seal) not @ad>20001229)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:30
7	2	5739880.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:24
8	7	(passivation near6 (film or layer)) near6 remov\$5 near6 boundary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:26
9	1	(passivation near6 (film or layer)) near6 remov\$5 near6 "non display"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:27
10	0	(passivation near6 (film or layer)) near6 remov\$5 near6 "border"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:29
11	435	(passivation near6 (film or layer)) near6 (distance or gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:29
12	49	349\$.ccls. and ((passivation near6 (film or layer)) near6 (distance or gap))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:29

13	14	(349\$.ccls. and ((passivation near6 (film or layer)) near6 (distance or gap))) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:43
14	17	(passivation near6 (film or layer)) near6 etch\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:36
15	30	(passivation near6 (film or layer)) near20 etch\$5 near20 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:43
16	43	(Ngo-Julie).xa. and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:46
17	40	((Ngo-Julie).xa. and seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:51
18	5	(Ngo-Julie).xa. and (passivation same seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:04
19	23	passivat\$5 near6 (etch\$10 or remov\$10) near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:55
20	6	(passivat\$5 near6 (etch\$10 or remov\$10) near6 seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:53
21	21	passivat\$5 near6 (etch\$10 or remov\$10) near6 boundary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:54
22	9	(passivat\$5 near6 (etch\$10 or remov\$10) near6 boundary) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:57
23	1	passivat\$5 near6 (etch\$10 or remov\$10) near6 "non display"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:54
24	0	passivat\$5 near6 exclud\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:55
25	57743	passivat\$5 not seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:56

26	1498	349\$.ccls. and (passivat\$5 not seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:57
27	724	(349\$.ccls. and (passivat\$5 not seal)) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:03
28	70	(passivation near6 (film or layer)) near6 form\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58
29	13	349\$.ccls. and ((passivation near6 (film or layer)) near6 form\$5 near6 seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58
30	35	(silicon or SiN) near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:02
31	19	((silicon or SiN) near6 remov\$5 near6 seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:07
32	2	(Ngo~Julie).xa. and (passivation near6 seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:04
33	19	(passivation near6 (film or layer)) near6 remov\$5 near6 adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:07
35	8	((passivation near6 (film or layer)) near6 remov\$5 near6 adhesive) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:37
36	18	(passivation near6 (film or layer)) near6 remov\$5 near6 seal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:21
37	1	(passivation near6 (film or layer)) near6 away near6 seal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:22
38	20	(passivation near6 (film or layer)) near6 overlap\$5 near6 seal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:22
39	58310	"thin film transistor" TFT	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:31

40	2	("thin film transistor" TFT) near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:33
41	2	("thin film transistor" TFT) near6 remov\$10 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:32
42	0	("thin film transistor" TFT) near6 etch\$10 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:33
43	3	("thin film transistor" TFT) near6 remov\$5 near6 boundary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:34
44	0	("thin film transistor" TFT) near6 remov\$5 near6 "non display"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:35
45	1	("thin film transistor" TFT) near50 remov\$5 near50 "non display"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:35
46	2	("thin film transistor" TFT) same remov\$5 same "non display"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:35
47	197	semiconductor near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:36
48	33373	349\$.ccls. and47	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:37
49	1	349\$.ccls. and (semiconductor near6 remov\$5 near6 seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:37
50	151	(semiconductor near6 remov\$5 near6 seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:05
51	6	438\$.ccls. and ((semiconductor near6 remov\$5 near6 seal) not @ad>20001229)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:38
52	2	(passivation near6 (film or layer)) near6 remov\$5 near6 perimeter	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:52

53	2	6552764.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:01
54	19	passivation near6 seal\$5 near6 adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:01
55	181611	protective near6 (film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:04
56	40	(protective near6 (film or layer)) near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:05
57	29	((protective near6 (film or layer)) near6 remov\$5 near6 seal) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:10
58	0	349\$.ccls. and (((protective near6 (film or layer)) near6 remov\$5 near6 seal) not @ad>20001229)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:06
59	58	organic near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:07
60	6	349\$.ccls. and (organic near6 remov\$5 near6 seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:09
61	108	seal\$5 near6 organic near6 adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:09
62	17	349\$.ccls. and (seal\$5 near6 organic near6 adhesion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:10
63	6	(349\$.ccls. and (seal\$5 near6 organic near6 adhesion)) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:14
64	1268	(349/153).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:13
65	58	((349/153).CCLS.) and passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:14

66	20	((((349/153).CCLS.) and passivation) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:58
67	618	protect\$5 near6 remov\$5 near6 seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:21
68	0	349\$.ccls. and (protect\$5 near6 remov\$5 near6 seal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:24
69	2	6552764.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:38
70	6	seal\$5 near6 contact\$5 near6 "gate insulating layer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:39
71	25	seal\$5 near6 contact\$5 near6 (gate near6 (insulat\$5 near6 film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:56
72	1	simultaneous near6 pattern\$5 near6 (passivation and active)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:57
73	0	simultaneous near6 etch\$5 near6 (passivation and active)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:57
74	48	mask near6 pattern\$5 near6 (passivation and active)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:00
75	14	349\$.ccls. and (mask near6 pattern\$5 near6 (passivation and active))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 16:58
76	2	(349\$.ccls. and (mask near6 pattern\$5 near6 (passivation and active))) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:00
77	11	mask near6 pattern\$5 near6 (passivation near6 active)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:00
78	2	(mask near6 pattern\$5 near6 (passivation near6 active)) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:07

79	79	pattern\$5 near6 (active near6 passivation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:07
80	28	349\$.ccls. and (pattern\$5 near6 (active near6 passivation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:07
81	5	(349\$.ccls. and (pattern\$5 near6 (active near6 passivation))) not @ad>20001229	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:12
82	6	seal near6 (screen near6 print\$5) near6 thermosett\$5 near6 fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:14
83	14	seal near6 thermosett\$5 near6 fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 17:14